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Research on High-Heat-Input Welding and Three-Dimensional Printing

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Deadline for manuscript
submissions:

closed (20 April 2024)

Message from the Guest Editor

Dear Colleagues,

This Special Issue aims to focus on high-heat-input welding, e.g., laser welding and plasma and welding, which involves welding with high-heat-input for obtaining greater welding efficiency than conventional welding processes.

We invite submissions of papers that address optimization of welding conditions, changes in mechanical properties after welding, numerical analysis based on the finite element of welding, challenges in 3D printing and WAAM (wire arc additive manufacturing), etc.



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Special Issue



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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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